

# 82430NX PCIset: Companion to the Highest Performance Pentium™ Processor

Hot Chips VI Symposium

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## Agenda

- ◆ Design Goals
- ◆ Architecture Overview
- ◆ Implementation Details
- ◆ Benchmark Results
- ◆ Summary

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## Design Goals

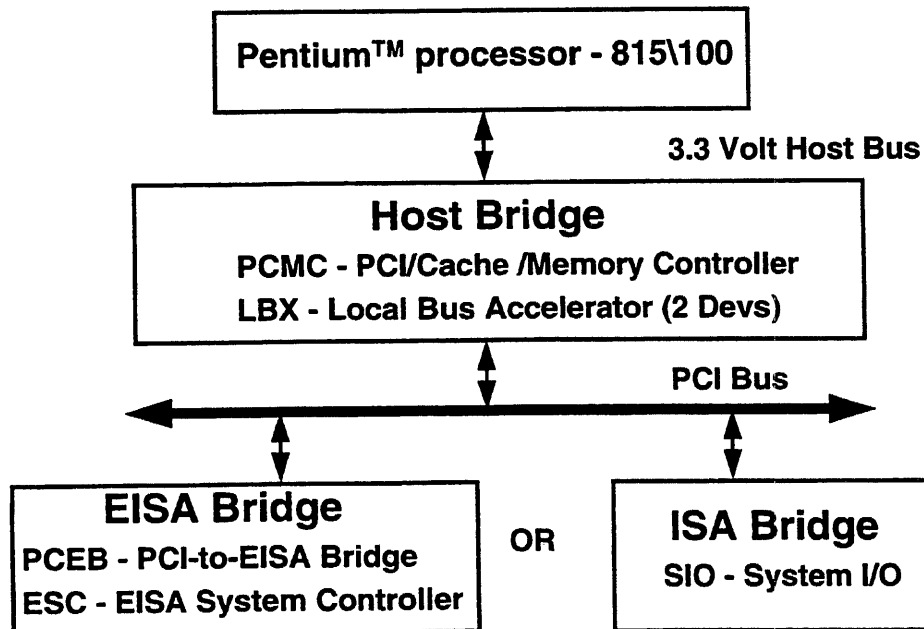
- ◆ Highest Performing Desktop System for the Pentium™ processor at iCOMP™ Index 815\100 MHz and Pentium processor - 735\90
- ◆ Uni- or Dual-Processor Designs with Maximum Performance and Minimum Complexity
- ◆ High Performance PCI Local Bus
- ◆ Enable Power Management on the Desktop
- ◆ Modular Architecture for EISA/ISA

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## 82430NX Overview - Components



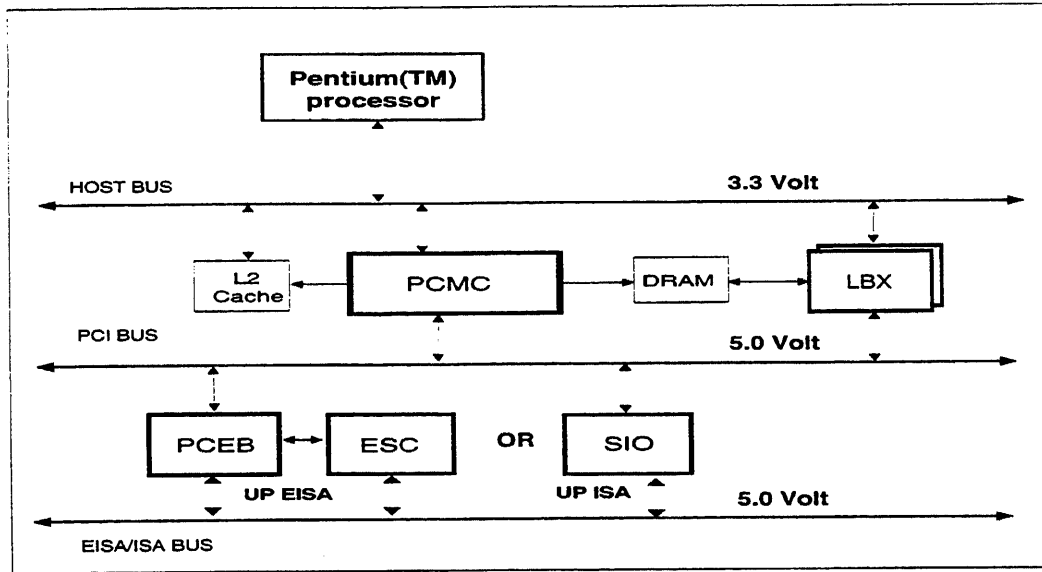
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# 82430NX System Diagram

## ◆ UP System with - ISA/EISA

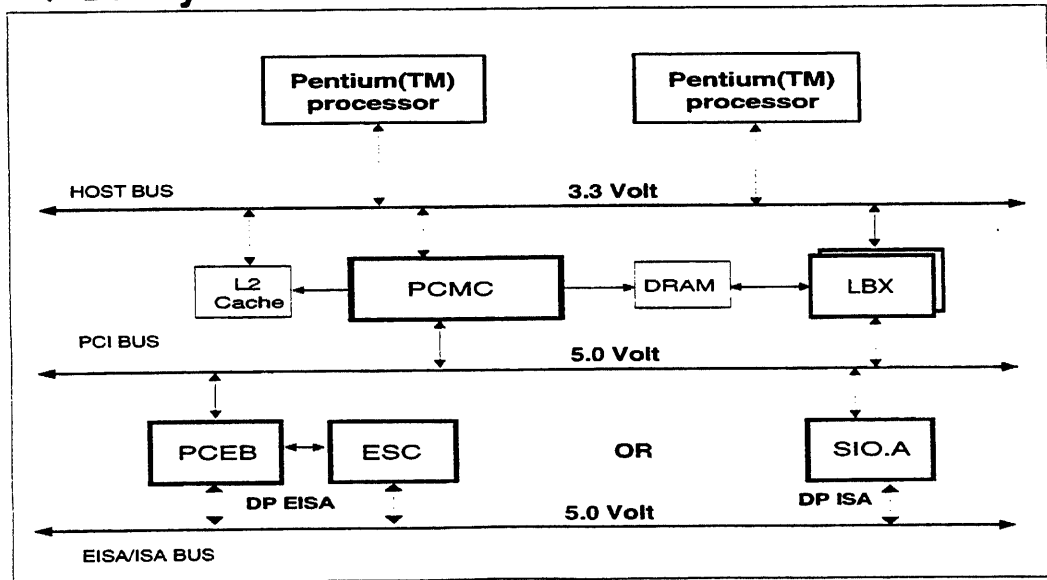


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# 82430NX System Diagram

## ◆ DP System with - ISA/EISA



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## 82430NX Overview - Features

- ◆ Supports Pentium™ processor at iCOMP™ Index 815\100 MHz and Pentium processor - 735\90
- ◆ 256/512K WB Burst or ASync Second Level Cache
  - Option configurations for multiple price points
- ◆ Integrated Tag Ram
  - Board space and cost savings
- ◆ Dual Processing Support
- ◆ Power Management Support
- ◆ 133 MB/Sec PCI Bus Transfer Rate
  - Designed for highest performance PCI
- ◆ Optional ISA or EISA Standard Bus Interface

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## 82430NX PCIset - Implementation Details

- ◆ PCIset Partitioning
- ◆ Optimized 3.3 Volt Host Bus Interface
- ◆ Dual Processing Capability
- ◆ Optimized L2 Cache/DRAM Controller
- ◆ High Performance PCI Local Bus Interface
- ◆ Power Management Support
- ◆ ISA/EISA Expansion Bus

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## 82430NX PCIset - Partitioning

### ◆ Host Bus

- PCI/Cache/Memory Controller (PCMC) - 208 pins, 2.0 W
- Local Bus Accelerator (LBX) - Two 160 pins, 1.4 W
- Both Components use 5 Volt core and 5V/3.3 V Buffers

### ◆ ISA Bridge

- System I/O (SIO) - 208 Pins, 1.0 W

### ◆ EISA Bridge

- PCI/EISA Bridge (PCEB) - 208 pins, 0.9 W
- EISA System Controller (ESC) - 208 pins, 0.7 W

*All Components are 0.8 micron in QFP Packages*

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## 82430NX PCIset - 3.3V Host Bus

### ◆ Main Features

- 64-Bit Data Path, 32 Bit Address w Pipelining
- Synchronous Operation at 60/66 MHz
- Burst Read/Write transfers to Cache/Memory

### ◆ Challenges

- All Host Bus Clocks Routed With Sub 1ns Clock Skew
- 66 MHz AC Analysis Provided Guidelines on Trace Lengths to meet Setup and Hold Requirements
- 4-Corner Simulations Met with DP Reference Platform

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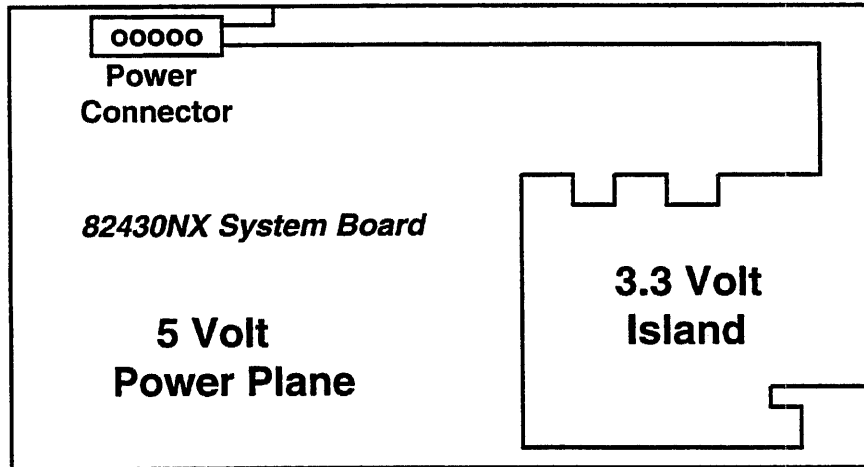
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# 82430NX PCiset: 3.3 Volt Power

## ◆ 3.3 Volt Power to PCiset and processors

- Use separate 3.3V power plane or 3.3V island (below)
- Power Supply: External or Voltage Regulated



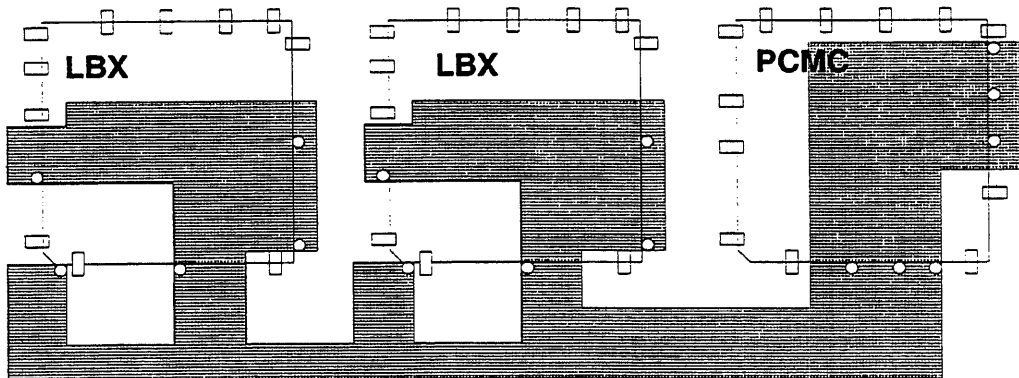
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# 82430NX PCiset: 3.3 Volt Power

## ◆ PCMC/LBX have "Split Ring" Pinout

- 5 Volts powers the Core, 3.3V powers the Host Bus I/F



□ = 5V PIN  
○ = 3.3V PIN

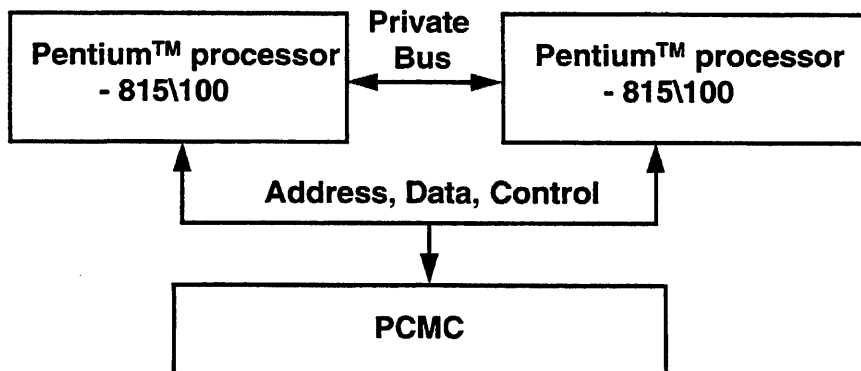


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## 82430NX PCIsset: Dual Processing

- ◆ Signals Common on Host Bus
  - Address, Data, Control, and 66 MHz Host Clock
  - Added Signals are CPU Arb. Bus and APIC
- ◆ “0” Extra Pins required on PCMC for DP

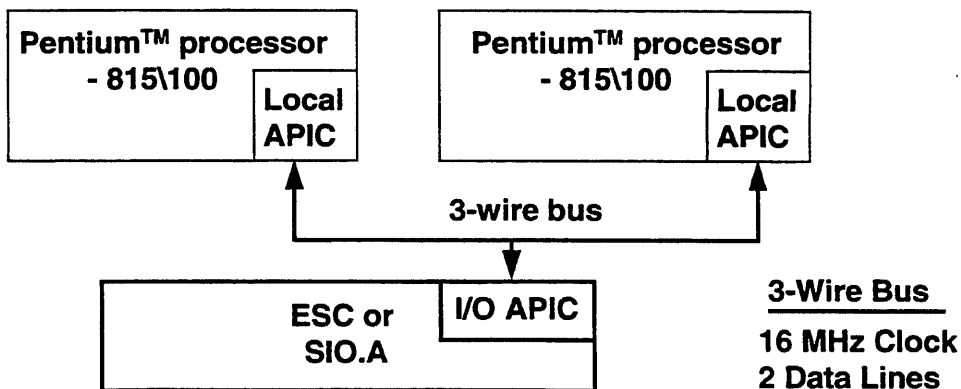


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## 82430NX PCIsset: Dual Processing

- ◆ I/O APIC Function is in the ESC or SIO.A
  - APIC Goal: Multiprocessor Interrupt Management
  - PCIsset, BIOS, and O/S vendor follow MP Spec V1.1



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## 82430NX PCIset - L2/DRAM I/F

### ◆ Second Level Cache

- 256K or 512K Direct-Map Write Back Cache
- Integrated Tag RAM for Board Space/Cost Reductions
- Burst SRAM with 3-1-1-1 Read/Write Timing
- Standard SRAM with 3/4-2-2-2 Read/Write Timing
- Fully Concurrency with PCI and Main Memory
- Byte Parity Optional

### ◆ DRAM Controller

- Burst Line Fill
- Cache Line Posting with 4-1-1-1 Timing
- Up to 512 MB DRAM
- Supports 5 Volt DRAM



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## 82430NX PCIset - PCI Local Bus

### ◆ CPU-to-PCI Local Bus Interface

- 133 MB/S PCI Local Bus Interface
- CPU posts data to PCI in 3 clocks
- "0-Wait State" 1 Clock Burst Writes on PCI

### ◆ PCI-to-Main Memory

- PCI Masters Posts Data into Main Memory via Two 4 Dword Buffers
- PCI Master Reads Data from Main Memory via 4 Quadword Buffer



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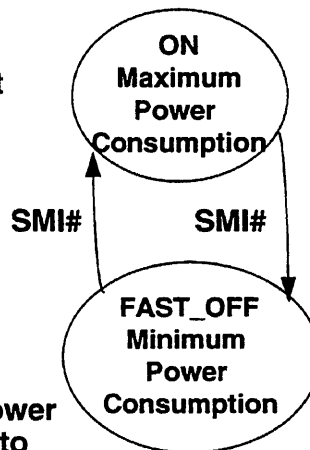




# 82430NX Power Management

## ◆ Power Management Features

- SMI# Interrupts: take the hardware in/out of power managed state
- SMM Space: PCIset provides 64K byte of protected area for SMM Code
- INTR Logic: selectable by user to create power down/up events
- STPCLK#: toggles high/low to reduce power on the processor, but still "ON" enough to perform critical tasks



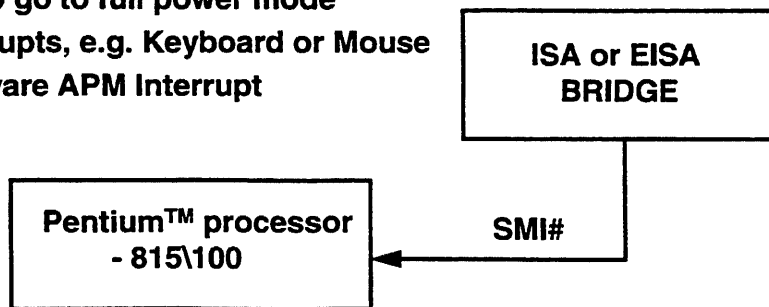
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# 82430NX Power Management

## ◆ Sources of System Management Intr. (SMI)

- Sources to enter power-down mode
  - FAST-Off Timer - driven by lack of interrupts
  - Software APM Interrupt
  - External "Power Management" Button
- Sources to go to full power mode
  - Interrupts, e.g. Keyboard or Mouse
  - Software APM Interrupt



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# Results

This Foil Reserved for:

- ◆ Benchmark Results
- ◆ Power Management Measurements



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## Summary of Key Points

We Have:

- ◆ Highlighted 82430NX PCIset Features
- ◆ Reviewed 3.3 Volt Requirements
- ◆ Discussed Dual Processing
- ◆ Detailed 82430NX Power Management



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